

TECHNICAL DATA SHEET

TDS 418/Index 04 - 01/01/2016





THERMIQUE PUTTY GLUE

HIGH TEMPERATURES SILICONE-FREE

DEFINITION

Putty glue for jointing and sealing, specially formulated to withstand very high temperatures.

ADVANTAGES

- Sealing industrial fluids (test compatibility or contact us for advice).
- Possesses excellent, long-lasting stability.
- Withstands temperatures up to 1,500°C without warping.
- Ready to use.
- Asbestos-free.
- Hardens completely, to the very centre.
- Good heat transfer.

APPLICATION FIELDS

Jointing and filling cracks, holes, or openings in metal, stone and concrete. Stoves, boilers, ovens, open fires, barbecues, chimneys, probes, etc. Automobile: sealing and gluing exhaust pipe connections. Do not use in contact with water, or in humid environments.

TECHNICAL CHARACTERISTICS

Aspect Colour	anthracite grey
Aspect after drying Base	
Density	1.65
Operating temperature Minimum/maximum thickness	

1/2 Manufacturing site and registered office

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INSTRUCTIONS FOR USE

Ready to use. Application temperature: +5°C to +40°C If the product is liquid when it comes out of the cartridge, this is due to light settling; should this happen, continue to pump until it becomes a homogeneous paste putty. Lightly roughen the surfaces to be glued. Apply the adhesive evenly on clean and dry surfaces.

Item can be used after 12 hours. Progressive reheating is recommended.

PACKAGING

310 ml cartridge

Ref. 1418 C3

x 12



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